

AMENDMENTS TO THE SPECIFICATION

Please cancel the originally-filed Abstract at page 18 and replace it with the following new Abstract.

ABSTRACT OF THE DISCLOSURE

A method of fabricating a circuit board is provided that includes forming a first layer of conductive material over an insulating layer, removing portions of the conductive material to define a first circuit pattern and a first rail area that is electrically isolated from the first circuit pattern, and removing portions of the conductive material from the first rail area. Optionally, the first rail area is positioned generally adjacent to a first edge of the circuit board and spans at least a portion of the length of the first edge. Optionally, portions of the conductive material of the first layer are removed to define a second rail area that is electrically isolated from the first circuit pattern and the first rail area, and portions of the conductive material of the first layer are also removed from the second rail area.